Smart Secure Platform (SSP);
Part 4: Embedded SSP (eSSP) Type 2 characteristics
(Release 17)
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Foreword

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z  the third digit is incremented when editorial only changes have been incorporated in the document.
The present document is part 4 of a multi-part deliverable covering Smart Secure Platform (SSP), as identified below:

Part 1: "General characteristics";
Part 2: "Integrated SSP (iSSP) characteristics";
Part 3: "Embedded SSP (eSSP) Type 1 characteristics";
Part 4: "Embedded SSP (eSSP) Type 2 characteristics".

Modal verbs terminology

In the present document "shall", "shall not", "should", "should not", "may", "need not", "will", "will not", "can" and "cannot" are to be interpreted as described in clause 3.2 of the ETSI Drafting Rules (Verbal forms for the expression of provisions).

"must" and "must not" are NOT allowed in ETSI deliverables except when used in direct citation.
1 Scope

The present document details the technical specifications for the Smart Secure Platform (SSP) in a discrete non removable hardware component, also known as eSSP. The present document defines specific attributes on top of the generic SSP specified in ETSI TS 103 666-1 [1] for eSSP Type 2, including the external interfaces (e.g. ISO 7816 [9], SPI, SWP). More in details the physical layer and related features are inherited from ETSI TS 103 666-3 [3] and the software architecture with virtualization interface, based on ETSI TS 103 666-2 [2].

2 References

2.1 Normative references

References are either specific (identified by date of publication and/or edition number or version number) or non-specific. For specific references, only the cited version applies. For non-specific references, the latest version of the reference document (including any amendments) applies.

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The following referenced documents are necessary for the application of the present document.

[1] ETSI TS 103 666-1: "Smart Secure Platform (SSP); Part 1: General characteristics".
[2] ETSI TS 103 666-2: "Smart Secure Platform (SSP); Part 2: Integrated SSP (iSSP) characteristics".
[3] ETSI TS 103 666-3: "Smart Secure Platform (SSP); Part 3: Embedded SSP (eSSP) Type 1 characteristics".
[4] ETSI TS 102 671: "Smart Cards; Machine to Machine UICC; Physical and logical characteristics".

NOTE: Available at https://globalplatform.org/specs-library/globalplatform-technology-virtual-primary-platform/.


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The following referenced documents are not necessary for the application of the present document but they assist the user with regard to a particular subject area.

Not applicable.

2.3 External references

The present document contains several references to other specifications, therefore required replacements as defined in ETSI TS 103 666-1 [1], clause 4.3 shall apply. As the present document targets the eSSP Type 2 class, word "SSP" from ETSI TS 103 666-1 [1] and the word "iSSP" from ETSI TS 103 666-2 [2] shall be replaced with "eSSP Type 2" as needed.

3 Definition of terms, symbols and abbreviations

3.1 Terms

For the purposes of the present document, the terms given in ETSI TS 103 666-1 [1], clause 3.1, ETSI TS 103 666-2 [2], clause 3.1 and ETSI TS 103 666-3 [3], clause 3.1 apply.

3.2 Symbols

Void.

3.3 Abbreviations

For the purposes of the present document, the abbreviations given in ETSI TS 103 666-1 [1], clause 3.3, ETSI TS 103 666-2 [2], clause 3.3 and ETSI TS 103 666-3 [3], clause 3.3 apply.

3.4 References to GlobalPlatform


NOTE: Care should be taken due to the fact that some clause numbers in the GlobalPlatform VPP specifications [5], [6], [7] and [8] may have changed compared to previous versions.

The provisions of ETSI TS 103 666-2 [2], clause 5.3 shall apply with the following exception:

- Tamper Resistant Element (TRE) refers to the eSSP Type 2.
4 Introduction

4.1 Overview

The present document defines an embedded secure element which allows different combinations of form factors, physical and electrical interfaces, transport layers, file system and security requirements based on the targeted use-case.

This secure element is called embedded Smart Secure Platform (eSSP) Type 2 and is a specific class of SSP defined in ETSI TS 103 666-1 [1]. This platform is defined to be flexible to use multiple physical interfaces and transport protocols.

The eSSP Type 2 implements virtualization interface as described in ETSI TS 103 666-1 [1], clause 5.2 and inherits all characteristics of eSSP Type-1 defined in ETSI TS 103 666-3 [3].

4.2 Document layout

The present document specifies:

- the eSSP Type 2 architecture, features and characteristics;
- the Primary Platform, including the hardware platform requirements and services;
- the Primary Platform Interface;
- the Secondary Platform Bundle;
- the communication interface, including the protocol stack layers;
- the certification requirements for the eSSP Type 2.

4.3 ASN.1 syntax

4.3.1 Introduction

The ASN.1 syntax defined in ETSI TS 103 666-1 [1], clause 4.4.1 shall apply.

4.3.2 Start of ASN.1

The complete ASN.1 code is provided for reference in Annex B. -- ASN1START

ESSPDefinitions { itu-t (0) identified-organization (4) etsi (0) smart-secure-platform (3666) part4 (4) }

DEFINITIONS
AUTOMATIC TAGS
EXTENSIBILITY IMPLIED ::= BEGIN
IMPORTS
/* Basic types */
maxUInt32, UInt32,
/* Common types */
UUID, URI, Certificates, VersionType
FROM
SSPDefinitions { itu-t (0) identified-organization (4) etsi (0) smart-secure-platform (3666) part1 (1) };

-- ASN1STOP

ETS1
5  eSSP Type 2 architecture

5.1  Overview
The provisions of ETSI TS 103 666-2 [2], clause 6.1 shall apply.

5.2  Functional Architecture
The provisions of ETSI TS 103 666-2 [2], clause 6.2 shall apply.

5.3  Security Perimeters
The provisions of ETSI TS 103 666-2 [2], clause 6.3 shall apply.

5.4  Unprivileged Execution Mode
The provisions of ETSI TS 103 666-2 [2], clause 6.4 shall apply.

5.5  Unprivileged Virtual Address Space
The provisions of ETSI TS 103 666-2 [2], clause 6.5 shall apply.

5.6  Run time Model
The provisions of ETSI TS 103 666-2 [2], clause 6.6 shall apply.

6  Primary Platform

6.1  Hardware Platform

6.1.1  Architecture
The provisions of GlobalPlatform VPP - Concepts and Interfaces [6], clause 3.1 shall apply with the following exceptions:
- the eSPP Type 2 shall contain an autonomous and independent clock system;
- the eSPP Type 2 shall contain communication functions;
- the eSPP Type 2 may contain the data protection hardware function.

6.1.2  Form factor
The eSSP Type 2 form factor may comply with ETSI TS 102 671 [4] with the exception of MFF1.

6.1.3  Security functions

6.1.3.1  Hardware Platform isolation
The provisions of ETSI TS 103 666-2 [2], clause 7.1.3.1 shall apply.
6.1.3.2 Memory Management Function
The provisions of ETSI TS 103 666-2 [2], clause 7.1.3.2 shall apply.

6.1.3.3 Key protection function
The provisions of ETSI TS 103 666-2 [2], clause 7.1.3.3 shall apply.

6.1.3.4 Remote audit
The provisions of ETSI TS 103 666-2 [2], clause 7.1.3.7 shall apply.

6.1.3.5 Security sensor function
The provisions of ETSI TS 103 666-2 [2], clause 7.1.3.8 shall apply.

6.1.4 Memories

6.1.4.1 Non Volatile Memories
The Primary Platform shall provide the Secondary Platform with direct memory-mapped access to its embedded NVM.

6.1.4.2 Volatile memory
The Primary Platform shall provide the Secondary Platform with direct memory-mapped access to its embedded volatile memory.

6.1.5 Communication functions
The physical communication interfaces between the Primary Platform and the hardware it is integrated with is outside the scope of the present document. These are abstracted from the Secondary Platform by the interface defined in clause 7.2.

6.1.6 Power

6.1.6.1 Power mode
The power modes defined in ETSI TS 103 666-3 [3], clause 6.2.1 shall apply.

6.1.6.2 Power sources

6.1.6.2.1 Types of power sources
The type of power source defined in ETSI TS 103 666-3 [3], clause 6.2.2.1 shall apply.

6.1.6.2.2 Power source of type Interface
The power source of type interface defined in ETSI TS 103 666-3 [3], clause 6.2.2.2 shall apply.

6.1.6.2.3 Power source of type Independent
The power source of type independent defined in ETSI TS 103 666-3 [3], clause 6.2.2.3 shall apply.

6.1.6.3 Power consumption
The power consumption defined in ETSI TS 103 666-3 [3], clause 6.2.3 shall apply.
6.1.7 Cryptographic functions
The provisions of ETSI TS 103 666-2 [2], clause 7.1.7 shall apply.

6.1.8 Clock
The eSSP Type 2 shall support a clock as defined in ETSI TS 103 666-3 [3], clause 6.3.

6.1.9 Secure CPU
The characteristics of the CPUs (e.g. endianness) are implementation dependent and outside the scope of the present document. The CPU(s) shall be based at least on a 32-bit architecture.

6.1.10 Random Number Generator
The provisions of ETSI TS 103 666-2 [2], clause 7.1.11 shall apply.

6.2 Low-level Operating System
The provisions of ETSI TS 103 666-2 [2], clause 7.2 shall apply.

6.3 Services
The provisions of ETSI TS 103 666-2 [2], clause 7.3 shall apply.

6.4 Minimum level of interoperability
The provisions of ETSI TS 103 666-2 [2], clause 7.4 shall apply.

6.5 Primary Platform identification
The eSSP Type 2 shall be identified with an identifier based on the definition in ETSI TS 103 666-2 [2], clause 7.5 with the following exceptions:

- **SSP Type** identifies the type of SSP and is coded as follows:

<table>
<thead>
<tr>
<th>Base-32 character</th>
<th>Value</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>F</td>
<td>'00101'</td>
<td>Embedded SSP Type 2 (eSSP Type 2)</td>
</tr>
</tbody>
</table>

6.6 Provisioning of Primary Platform software
The provisions of GlobalPlatform VPP - Concepts and Interfaces [6], clause 5.7 REQ85 shall apply.

6.7 Part Number Identifier
The provisions of ETSI TS 103 666-2 [2], clause 7.7 shall apply.
7 Primary Platform Interface

7.1 Kernel functions ABI/API
The provisions of ETSI TS 103 666-2 [2], clause 8.1 shall apply.

7.2 Communication service interface
The provisions of ETSI TS 103 666-2 [2], clause 8.2 shall apply with the exception listed below:
- One of the end points of any dynamic pipe may be out the SSP host domain.

7.3 Secondary Platform Bundle management service interface
The provisions of ETSI TS 103 666-2 [2], clause 8.3 shall apply.

8 Secondary Platform Bundle

8.1 Introduction
The Secondary Platform Bundle refers to either the data container or the runtime instance of the container.

8.2 States
The provisions of ETSI TS 103 666-2 [2], clause 9.2 shall apply.

8.3 Secondary Platform Bundle container format
The provisions of ETSI TS 103 666-2 [2], clause 9.3 shall apply.

8.4 Secondary Platform

8.4.1 High-level OS
The provisions of ETSI TS 103 666-2 [2], clause 9.4.1 shall apply.

8.4.2 Execution framework
The provisions of ETSI TS 103 666-2 [2], clause 9.4.2 shall apply.

8.4.3 UICC platform as a Secondary Platform
The provisions of ETSI TS 103 666-2 [2], clause 9.4.3 shall apply.
8.4.4 Capability exchange

8.4.4.1 Overall description

The capability exchange procedure is used to inform the eSSP Type 2 of the capabilities of the terminal and for the terminal to retrieve the capabilities of the eSSP Type 2.

The capability exchange for eSSP Type 2 supporting SCL as defined in ETSI TS 103 666-1 [1], clause 6.4.2 apply with modifications provided below.

8.4.4.2 Capabilities of the terminal

The data field sent by the terminal to the eSSP Type 2 contains the data structure defined in ETSI TS 103 666-3 [3], clause 6.4.2.2.

8.4.4.3 Capabilities of the eSSP Type 2

The provisions of ETSI TS 103 666-3 [3], clause 6.4.2.3 shall apply with the following exception:

- SSPClass field shall have the eSSPClасс-Embedded-Type2 (2) value.

8.4.5 Identifiers of Secondary Platform Bundle

The provisions of ETSI TS 103 666-2 [2], clause 9.4.5 shall apply.

8.5 SSP Application

The provisions of ETSI TS 103 666-2 [2], clause 9.5 and subclauses shall apply.

8.6 Lifecycle management of Secondary Platform Bundles

The provisions of ETSI TS 103 666-2 [2], clause 9.6 shall apply.

8.7 Secondary Platform Bundle family identifier

The provisions of ETSI TS 103 666-2 [2], clause 9.7 shall apply.

8.8 eSSP Type 2 suspension

If the eSSP Type 2 indicates it supports the suspension mechanism as defined in clause 8.4.4.3, the provisions defined in ETSI TS 103 666-1 [1], clause 6.9 shall apply with the modifications listed below:

- The suspension of the SSP should only be used if, in addition to the Secondary Platform Bundle Loader, only one Secondary Platform Bundle is Enabled on an eSSP Type 2.
- The Secondary Platform Bundle Enabled shall support the suspension mechanism.
- The Terminal shall not suspend the eSSP Type 2 if a Secondary Platform Bundle provisioning procedure is ongoing.

NOTE: Suspension of eSSP Type 2 with multiple Secondary Platform Bundle is FFS.
9 Communication interface

9.1 eSSP Type 2 initialization

The eSSP Type 2 interface session defined in ETSI TS 103 666-1 [1], clause 6.4.1 shall apply.

9.2 Low level protocol layers

9.2.1 Physical layer

9.2.1.1 Overview

The provisions of ETSI TS 103 666-3 [3], clause 7.1 shall apply.

9.2.1.2 Reset

The eSSP Type 2 description in ETSI TS 103 666-3 [3], clause 7.2 shall apply.

9.2.1.3 SPI interface

The eSSP Type 2 may support an SPI interface, in that case the clauses ETSI TS 103 666-3 [3], clause 7.4 and subclauses shall apply.

9.2.1.4 I2C interface

The eSSP Type 2 may support an I2C interface, in that case the clauses ETSI TS 103 666-3 [3], clause 7.5 and subclauses shall apply.

9.2.1.5 SWP interface

The eSSP Type 2 may support an SWP interface, in that case the clauses ETSI TS 103 666-3 [3], clause 7.6 and subclauses shall apply.

9.2.1.6 USB interface

The eSSP Type 2 may support an USB interface, in that case the clauses ETSI TS 103 666-3 [3], clause 7.7 and subclauses shall apply.

9.2.2 Link layer

The provisions of ETSI TS 103 666-1 [1], clause 8.3.1 shall apply.

9.3 SSP Common Layer

9.3.1 introduction

The eSSP Type 2 shall support the SCL protocol, therefore the provisions defined in ETSI TS 103 666-1 [1], clause 8 and subclauses shall apply, with the exception listed below:

- The SCL network controller host and SCL router need not to share the same security perimeter of the eSSP Type 2, i.e. the SCL network controller host and SCL router are not required to have an equivalent level of security when compared with the eSSP Type 2.

Each Secondary Platform Bundle is responsible for the implementation of the SCL protocol as needed for its operation.
9.3.2 eSSP Type 2 with only one SCL interface

If the eSSP Type 2 has only one SCL interface, this interface should convey packets to multiple SCL hosts outside the SSP host domain, as illustrated in ETSI TS 103 666-3 [3], clause B.1.

9.3.3 eSSP Type 2 with multiple SCL interfaces

If the eSSP Type 2 has multiple SCL interfaces, all these interfaces should belong to the same SCL network. Furthermore, the eSSP Type 2 should implement the SCL router and SCL network controller host, as illustrated in ETSI TS 103 666-3 [3], clause B.2.

SCL hosts of an host domain should be accessible only through one SCL interface. The communication inside the eSSP Type 2 between the eSSP Type 2 Host, the router and the SCL network controller host are out of the scope of the present document.

9.4 Communication layers above SCL

The definition and usage of protocols layers above the SCL (e.g. ISO 7816 [9] APDUs) are defined in ETSI TS 103 666-1 [1], clause 10.

10 Certification

10.1 Introduction

The eSSP Type 2 shall be able to support a certification by composition of a Secondary Platform Bundle from the Primary Platform certification.

10.2 Primary Platform certification

10.2.1 Overview

The provisions of GlobalPlatform VPP - Concepts and Interfaces [6], clause 4 shall apply. The certification of the Primary Platform shall include the Loader Package 2, as defined in BSI-CC-PP-0084-2014 [10].

10.2.2 Security Capabilities

The provisions of ETSI TS 103 666-2 [2], clause 11.2.2 shall apply.

10.3 Secondary Platform Bundle certification

The provisions of ETSI TS 103 666-2 [2], clause 11.3 shall apply.

11 eSPP Type 2 ecosystem and interfaces

The provisions of ETSI TS 103 666-2 [2], clause 12 and subclauses shall apply.
Annex A (normative):
Additions for Telecom Secondary Platform Bundles

The provisions of ETSI TS 103 666-2 [2], Annex A shall apply.
Annex B (normative): ASN.1 definitions

B.1 End of ASN.1

```asn1
-- ASN1START
END
-- ASN1STOP
```

B.2 Complete ASN.1 file

The complete ASN.1 definition, as generated merging all the ASN.1 snippets present in the present document is available here:

```asn1
ESSPDefinitions { itu-t (0) identified-organization (4) etsi (0) smart-secure-platform (3666) part4 (4) }
DEFINITIONS AUTOMATIC TAGS EXTENSIBILITY IMPLIED ::=
BEGIN IMPORTS /* Basic types */ maxUInt32, UInt32, /* Common types */ UUID, URI, Certificates, VersionType */ FROM SSPDefinitions { itu-t (0) identified-organization (4) etsi (0) smart-secure-platform (3666) part1 (1) };
END
```
### History

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